



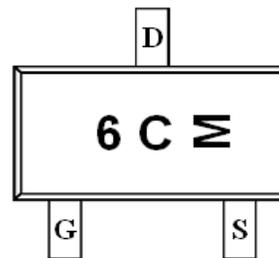
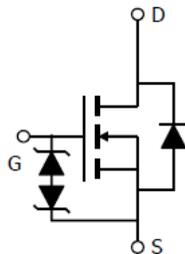
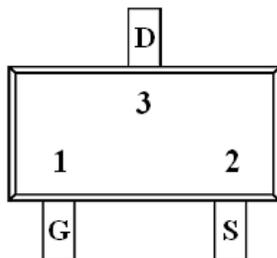
General Description

AFN1330S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge. These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- 60V/0.5A , $R_{DS(ON)}=7500m\Omega@V_{GS}=10V$
- 60V/0.05A , $R_{DS(ON)}=7500m\Omega@V_{GS}=5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- ESD Protection (1KV) Diode design-in
- SOT-323 package design

Pin Description (SOT-323)



Application

- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

Pin Define

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN1330SS32RG	6CM	SOT-323	Tape & Reel	3000 EA

- ※ 6C Parts code
- ※ M Month code
- ※ AFN1330SS32RG : 7" Tape & Reel ; Pb- Free ; Halogen -Free



Absolute Maximum Ratings

($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current($T_J=150^\circ\text{C}$)	I_D	$T_A=25^\circ\text{C}$	0.115
		$T_A=70^\circ\text{C}$	0.075
Pulsed Drain Current	I_{DM}	0.8	A
Continuous Source Current(Diode Conduction)	I_S	0.115	A
Power Dissipation	P_D	225	mW
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C/W}$

Electrical Characteristics

($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.6	2.0	V
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			3	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$			1	μA
		$V_{DS}=60V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			10	
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=0.5A$		1400	7500	m Ω
		$V_{GS}=5V, I_D=0.05A$		1800	7500	
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=0.2A$	80			mS
Diode Forward Voltage	V_{SD}	$I_S=0.115A, V_{GS}=0V$			1.5	V
Dynamic						
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V$ $f=1\text{MHz}$		17	50	pF
Output Capacitance	C_{oss}			10	25	
Reverse Transfer Capacitance	C_{rss}			3	5	
Turn-On Time	$t_{d(on)}$	$V_{DD}=25V, R_L=50\Omega$ $I_D \cong 0.5A, V_{GEN}=10V, R_G=25\Omega$		7	20	ns
Turn-Off Time	$t_{d(off)}$			11	40	



Typical Characteristics

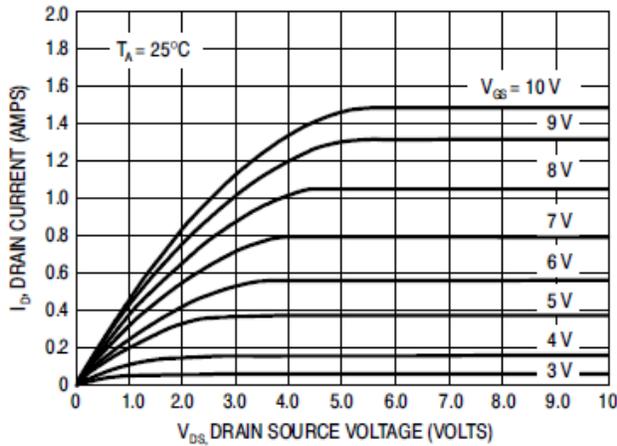


Figure 1. Ohmic Region

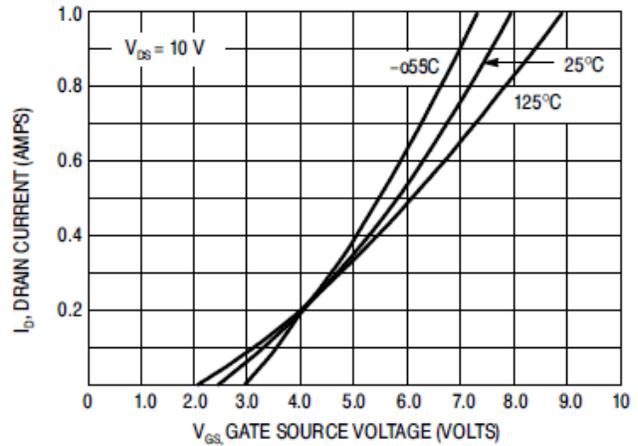


Figure 2. Transfer Characteristics

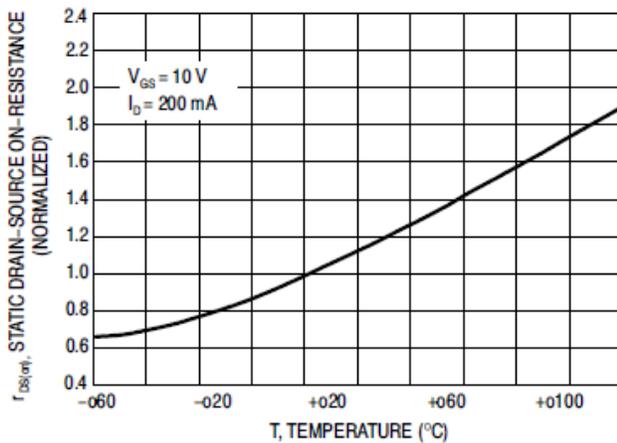


Figure 3. Temperature versus Static Drain-Source On-Resistance

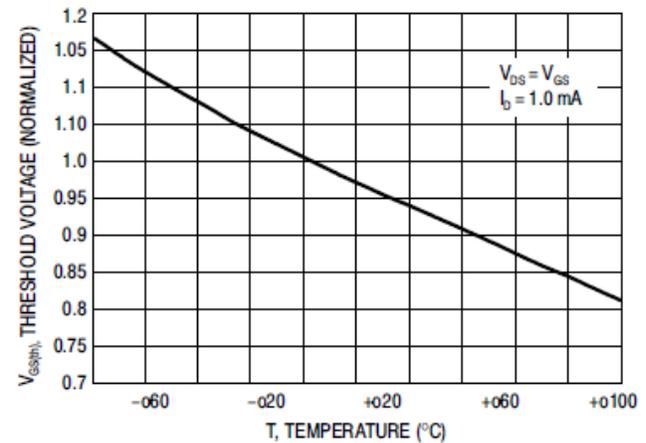
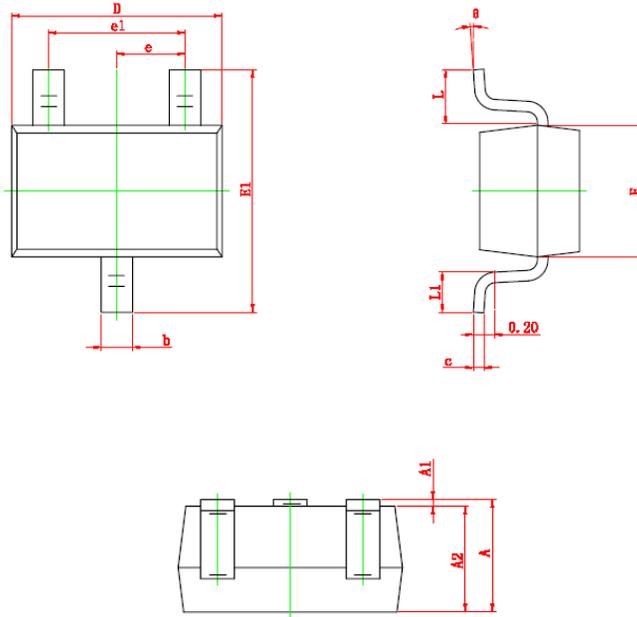


Figure 4. Temperature versus Gate Threshold Voltage



Package Information (SOT-323)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

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